Attorney Docket No. 1572.1252

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent	Applica	ition of:	
Se-Young J	ANG et	al	
Application No.:			Group Art Unit:
Filed: April 1	3, 2004	4	Examiner:
For: SUR	FACE-	MOUNTING METHOD OF SEM	ICONDUCTOR CHIP ON PCB
		INFORMATION DISCLOS	SURE STATEMENT
Commission PO Box 145 Alexandria,	0		
Sir:			
provided cer subject U.S.	tain inf patent	ormation that the Examiner may	ovisions of 37 CFR § 1.56, there is hereby consider material to the examination of the the Examiner make this information of record bject application.
1. Enclosures accompanying this Information Disclosure Statement are:		nation Disclosure Statement are:	
11 10 10		application or a PCT Internation English language translation (c each non-English language pu Explanations of Relevancy of F	complete or relevant portion(s)) attached to
2. [⊠ In a	accordance with 37 CFR § 1.98, derstood to be the relevance of e	a concise explanation of what is presently each non-English language publication is
2:	а. 🗌	enclosed "English-language ve indicates the degree of relevar 609, Minimum Requirements for	s 2a, 2b, 2c and/or 2d) ish language publications were cited on the ersion of the search report or action which nce found by the foreign office". (See MPEP or an Information Disclosure Statement, Part Relevance, pp. 600-100 to 600-101, Rev. 1,
2	b. 🖂	set forth in the application.	

2c. ☐ 2d. ⊠	satisfied because an English language translation (complete or relevant portion(s)) is attached to each non-English language publication. enclosed as Attachment 1(e), hereto.
to be, ma (other the	ision is made that the information cited in this Statement is, or is considered iterial to patentability nor a representation that a search has been made an search report(s) from a counterpart foreign application or a PCT anal Search Report, if submitted herewith). 37 CFR §§ 1.97(g) and (h).
	Respectfully submitted,
	STAAS & HALSEY LLP
Dated: April 13, 20 1201 New York Ave Washington, D.C. 2 Telephone: (202) 43 Facsimile: (202) 434	, N.W., Suite 700 Gene M. Garner II 0005 Registration No. 34,172 4-1500

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FORM PTO-1449

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

ATTORNEY DOCKET NO. 1572.1252 FIRST NAMED INVENTOR Se-Young JANG et al

LIST OF REFERENCES CITED BY APPLICANT

(Use several sheets if necessary)

FILING DATE	GROUP ART UNIT
April 13, 2004	GROOF ART OWN

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NO.	DATE	NAME	CLASS	SUB- CLASS	FILING DATE
	AA	2002/0089067	7/11/02	Crane et al.			
	АВ	2003/0038342	2/27/03	Standing			
	AC	2003/0045028	3/6/03	Tsao et al.			
	AD	5,710,071	1/20/98	Beddingfield et al.			
	AE	6,201,301	3/13/01	Hoang			
	AF	6,507,119	1/14/03	Huang et al.			

FOREIGN PATENT DOCUMENTS

		TOILE	IGIT I ATENT BOOGINEIT				
	DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB- CLASS	TRANSL YES	ATION NO
A	G 10-0326108	2/14/02	Korea				Х
Al	H 2002-63628	8/3/02	Korea				X
Al	2002-33944	5/8/02	Korea				X
A	2002-43755	6/12/02	Korea				X
Al	< 2002-91916	10/23/01	Korea				X
A	2002-14861	2/20/03	Korea				X
A	M 2002-44577	6/15/02	Korea				X
Α	N 2002-28454	4/8/03	Korea				X
A	0 1 256 387	11/13/02	European				

OTHER REFERENCES (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)

			TRANSL YES	NO NO
	AM			
EXAMINER	<u> </u>	DATE CONSIDERED		

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

ATTACHMENT 1(e)

OF REFERENCES

ATTORNEY DOCKET NO.	APPLICATION NO.
1572.1252	
FIRST NAMED INVENTOR	
Se-Young JANG et al	
FILING DATE	GROUP ART UNIT
April 13, 2004	

Korean Patent No. 10-326108 is generally related to a Method of Surface-Mounting Semiconductor Chip on PCB.

Korean Publication No. 2002-63628 is generally related to a Method of Surface-Mounting Semiconductor Chip on PCB.

Korean Publication No. 2002-33944 is generally related to a Method of Surface-Mounting Semiconductor Chip on PCB.

Korean Publication No. 2002-43755 is generally related to a Method of Surface-Mounting Semiconductor Chip on PCB.

Korean Publication No. 2002-91916 is generally related to a Method of Surface-Mounting Semiconductor Chip on PCB.

Korean Publication No. 2002-14861 is generally related to a Method of Surface-Mounting Semiconductor Chip on PCB.

Korean Publication No. 2002-44577 is generally related to a Method of Surface-Mounting Semiconductor Chip on PCB.

Korean Publication No. 2002-28454 is generally related to a Method of Surface-Mounting Semiconductor Chip on PCB.